molex

Part Number : 1706732278

Product Description : EdgeLine Vertical Connector, 12.5 Gbps, 0.80mm Pitch, 1.57mm PCB Thickness, 2 Bays, 278 Circuits

Series Number : 170673

Status : Active

Product Category : Card Edge Connectors

Documents & Resources

Drawings

Drawing 1706732278_sd.pdf

Packaging Design Drawing PK-76693-900-001.pdf

3D Models and Design Files

Electrical Model Document 1706730002-000.pdf

Specifications

Application Specification AS-76693-100-001.pdf

Application Specification AS-76693-101-001.pdf

Product Specification PS-75594-999-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	ⓔ
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)3788-DC (14 Jun 2023)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration

- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	Card Edge Connectors
Series	170673
Description	EdgeLine Vertical Connector, 12.5 Gbps, 0.80mm Pitch, 1.57mm PCB Thickness, 2 Bays, 278 Circuits
Component Type	Edgecard to PCB
Product Family	EdgeLine High-Speed Connectors
Product Name	EdgeLine
Standard Based	General
UPC	884982404557

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	1.5A
Data Rate	12.5-20.0 Gbps
High Power Bay (30.0A or more)	No
Voltage - Maximum	250V AC

Physical

Circuit Size Range	201-294 Circuits
Circuits (Loaded)	278
Circuits (maximum)	278
Color - Resin	Black
Durability (mating cycles max)	200
Edge Card Thickness	1.57mm

Entry Angle	N/A
Flammability	94V-0
Keying to Mating Part	N/A
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	12.000/g
Orientation	Vertical
Packaging Type	Tray
PCB Locator	No
PCB Thickness - Recommended	2.79mm
Pitch - Mating Interface	0.80mm
Pitch - Termination Interface	0.80mm
Plating min - Mating	0.762µm
Plating min - Termination	0.762µm
Polarized to Mating Part	Yes
(p)ower-(s)ignal Configuration	278s - 0p
Temperature Range - Operating	-40° to +105°C
Termination Interface Style	Through Hole - Compliant Pin

Solder Process Data

Lead-Free Process Capability	N/A

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